

METHOD FOR GRINDING OF GLASS SUBSTRATE

Abstract of the Disclosure

The present invention provides a method for grinding a glass substrate, which comprises (1) interposing a glass substrate held by a plurality of carriers, between an upper surface plate and a lower surface plate both constituted by fixed abrasive particles and (2) applying, to the glass substrate, a pressure and a rotary motion by the two plates to grind the both sides of the glass substrate, to obtain the glass substrate having a flatness of 10 μm or less and a surface roughness (Ra) of 0.0005 to 0.05 μm , after the grinding. The method has shortened the conventional steps of thickness processing of glass substrate to one step and thereby has enabled significant reductions in material cost, cost of processing equipment, cost of material lost in processing, processing time, etc.